

Ultra-Low Capacitance ESD Diode Array

 ESD / transient protection of high-speed data lines exceeding

IEC61000-4-2 (ESD): 20 kV (air / contact)

IEC61000-4-4 (EFT): 40 A (5/50 ns)

IEC61000-4-5 (surge): 3 A (8/20 μs)

• Max. working voltage: 5.3 V

• Extremely low capacitance: down to 0.2 pF

• Very low clamping voltage: 12 V typ.

Extremely low forward clamping voltage: 4 V typ.

• Very low reverse current: < 1 nA typ.

• Pb-free (RoHS compliant) package

Qualified according AEC Q101

Applications

- USB 2.0, 10/100/1000 Ethernet, FireWire, DVI HDMI, S-ATA
- Mobile communication
- Consumer products (STB, MP3; DVD, DSC...)
- LCD displays, camera
- Notebooks and destop computers, peripherals





ESD5V3U2U-03F ESD5V3U2U-03LRH



Type	Package	Configuration	Marking
ESD5V3U2U-03F	TSFP-3	2 lines, uni-directional*	Z1
ESD5V3U2U-03LRH	TSLP-3-7	2 lines, uni-directional*	Z1

^{*} or 1 line, bi-directional between pins 1 and 2, if pin 3 is not connected





Maximum Ratings at $T_A = 25$ °C, unless otherwise specified

Parameter	Symbol	Value	Unit
ESD contact/ air discharge ¹⁾	V _{ESD}	20	kV
Peak pulse current $(t_p = 8 / 20 \mu s)^2$	I _{pp}	3	Α
Operating temperature range	T_{op}	-40125	°C
Storage temperature	$T_{\rm stg}$	-65150	

Electrical Characteristics at $T_A = 25$ °C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Characteristics					
Reverse working voltage	V_{RWM}	-	-	5.3	V
Breakdown voltage	$V_{(BR)}$	6	-	-	
$I_{(BR)} = 1 \text{ mA}$, from pin 1 to 3					
Reverse current	I_{R}		< 1	50	nA
V_{R} = 5.3 V, from pin 1 to 3					
Clamping voltage	V_{CL}				V
$I_{PP} = 1 \text{ A}, t_p = 8/20 \mu \text{s}^{2}, \text{ from } 1/2 \text{ to } 3$		-	10	13	
$I_{PP} = 3 \text{ A}, t_p = 8/20 \mu \text{s}^{2}, \text{ from 1/2 to 3}$		-	12	15	
Forward clamping voltage	V_{FC}				
$I_{PP} = 1 \text{ A}, t_p = 8/20 \mu \text{s}^{2}, \text{ from 3 to } 1/2$		-	2	4	
$I_{PP} = 3 \text{ A}, t_p = 8/20 \mu \text{s}^{2}, \text{ from 3 to } 1/2$		-	4	6	
Line capacitance, $V_R = 0 \text{ V}$, $f = 1 \text{ MHz}$	C _T				pF
from pin 1/2 to 3 ³⁾		-	0.4	0.6	
from pin 1 to 2, pin 3 not connected		-	0.2	0.4	

 $^{^{1}}V_{\mbox{ESD}}$ according to IEC61000-4-2

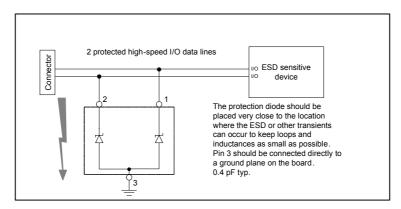
 $^{^2}I_{\mbox{\footnotesize pp}}$ according to IEC61000-4-5

³Total capacitance line to ground



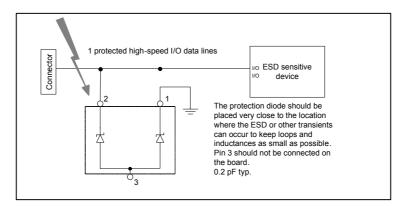
Application example ESD5V3U2U...

2 lines, uni-directional



Application example ESD5V3U2U...

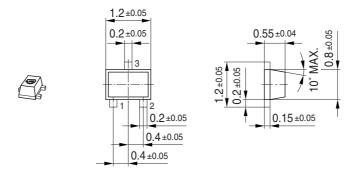
1 line, bi-directional



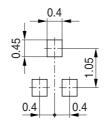
3 2008-07-10



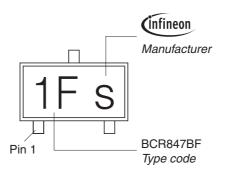
Package Outline



Foot Print

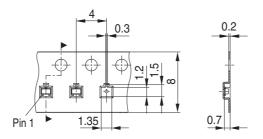


Marking Layout (Example)



Standard Packing

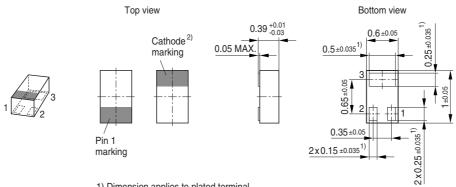
Reel ø180 mm = 3.000 Pieces/Reel Reel ø330 mm = 10.000 Pieces/Reel



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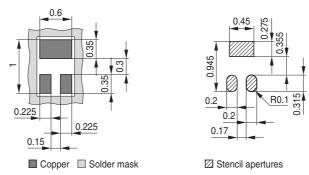
Package Outline



- 1) Dimension applies to plated terminal
- 2) Only for diodes, cathode marking on pin 3

Foot Print

For board assembly information please refer to Infineon website "Packages"

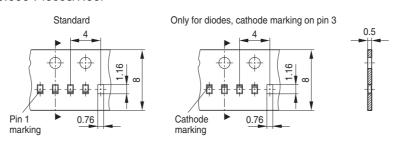


Marking Layout



Standard Packing

Reel ø180 mm = 15.000 Pieces/Reel



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